SynPower －Co-Create to make better!

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Outline

I. Company Profile

II. Operational Overview

III. Outlook and Strategy

➢SynPower – Intelligent Manufacturing Integration Services

Main Operating Locations

◆ Taiwan Operating Location: Taoyuan District

Mainland Operating Locations: Kunshan, Dongguan, Huai'an, Qinhuangdao

Overseas Operating Locations: Bangkok, Thailand; Chennai, India

Close to Demand, Localized Service

- ◆ Established : May, 2002
- ◆ Capital Amount : 329 million
- ◆ Number of Employees: Approximately 300

Committed to automation equipment and machine vision application business in industries such as circuit boards and semiconductors.

➢ Subsidiaries :

- ● SynTop : Various horizontal wet process equipment
- ● Chipboard Technology : PCB surface treatment OEM

➢ Industry Position (Relationships within the Industry's Upstream, Midstream, and Downstream)

Upstream

- Precision Machinery Components
- Specialty Materials
- Optical Components
- Tooling Industry
- Programming
- Other Components

MITSUBISHI ELECTRIC Changes for the Better 三菱電機
HIWIN 上銀科技
HITACHI Inspire the Next
TELEDYNE DALSA Everywhereyoulook™
FOTEK 陽明電機股份有限公司 FOTEK CONTROLS CO.,LTD
OMRON AUTOMATION
MATROX IMAGING
MK Chem & Tech
JCU
UYEMURA

Midstream

- Equipment Manufacturer
- Equipment agents
- System integration

SynPower

Downstream

- PCB Industry
- IC Substrate
- Optoelectronic Semiconductors
- Other Manufacturing Industries

臻鼎科技集團 Zhen Ding Tech. Group
Unimicron 欣興電子
COMPEQ 華通電腦股份有限公司
南亞電路板

➢The New Factory under construction in Qingpu

Location : Lane 255, Section 3, Xinsheng Road

THSR Taoyuan Station <10min

Neili Interchange <15min

- ◆ Expected to be operational in August 2025
- ◆ Floor Area (including Basement Level 1) : 3,600 Pin
- ◆ New Factory Exterior Renderings:

➢ Net Zero Carbon Emissions Policy Target, with Gradual Implementation of Carbon Reduction Measures by 2050

I. Company Profile

Establish energy management system

EMS

主動式能源管理
定期報表系統
Email/Line

冰水節能控制

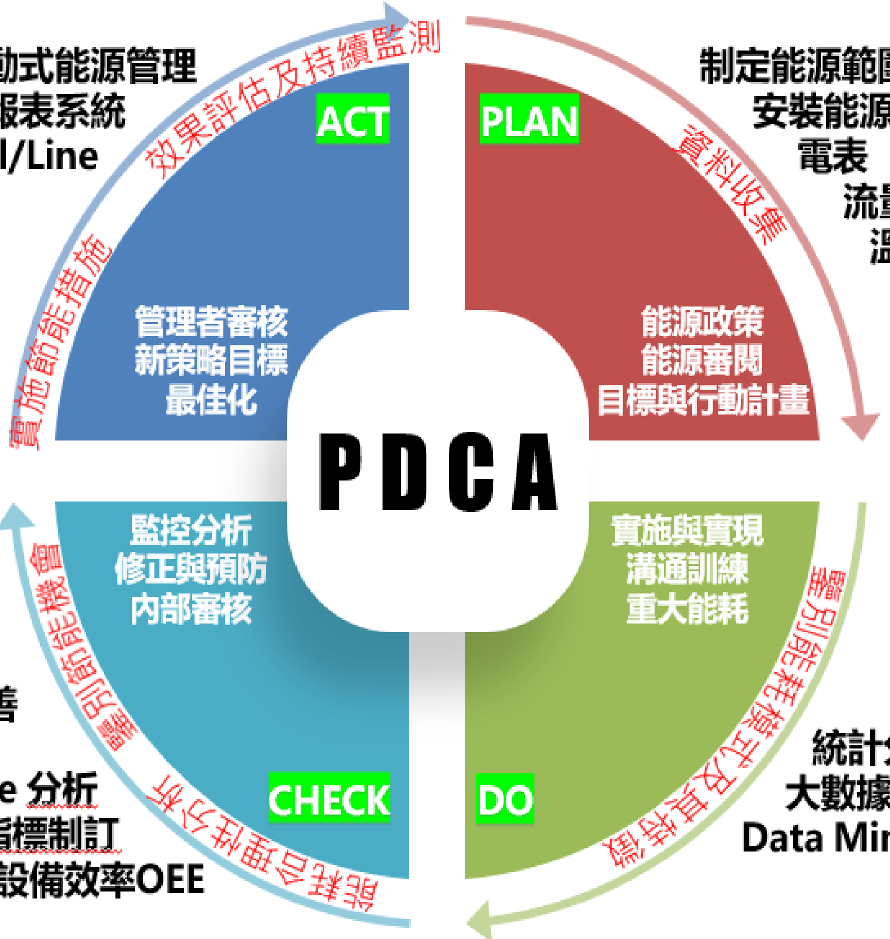
最佳化模型
最佳化控制

EMS

硬體改善
排程改善
控制邏輯
行為改善

EMS

能源基線Baseline 分析
能源績效指標制訂
綜合設備效率OEE



PDCA

PLAN
能源政策
能源審閱
目標與行動計畫

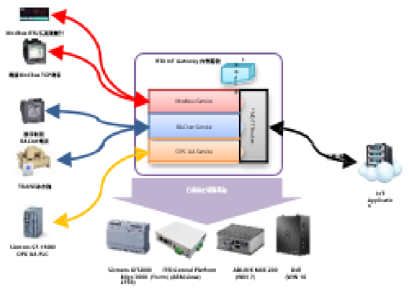
DO
實施與實現
溝通訓練
重大能耗

CHECK
監控分析
修正與預防
內部審核

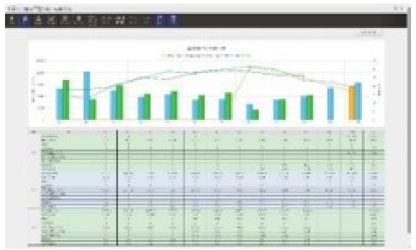
ACT
管理者審核
新策略目標
最佳化

資料收集
鑑別能耗模式及其特徵
能耗合理性分析
鑑別節能機會
實施節能措施
效果評估及持續監測

制定能源範圍
安裝能源量測項目
電表
流量計
溫度
壓力



EMS



統計分析
大數據分析
Data Mining

➢ Corporate Social Responsibility

Ruth Society For Disability Services Bade Spring Fair on March 23, 2024

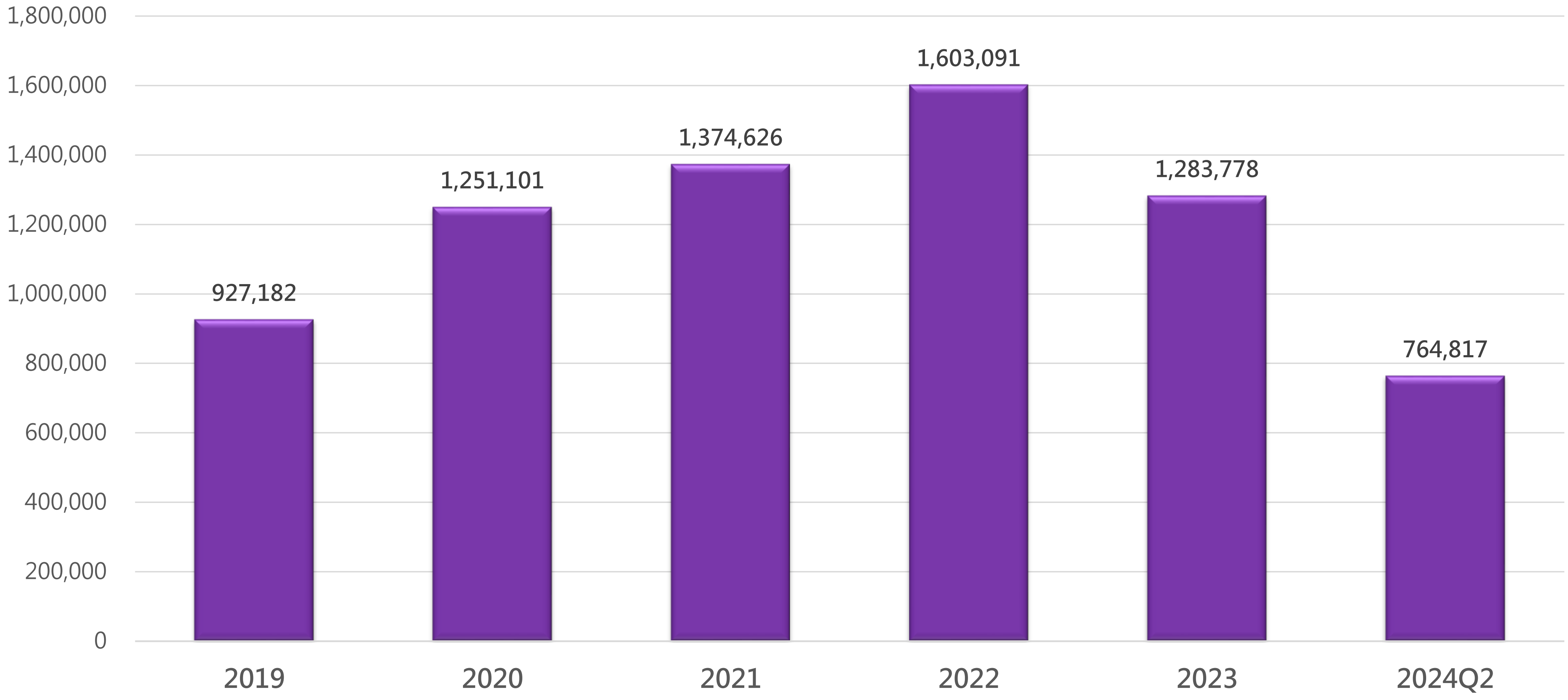
Chinese Fund for Children and Families - Slow Learners "Slow Fly" Event on November 11, 2023

Autism Foundation - Exceptional Concert on November 30, 2023

➢ Sales Performance - Performance Report

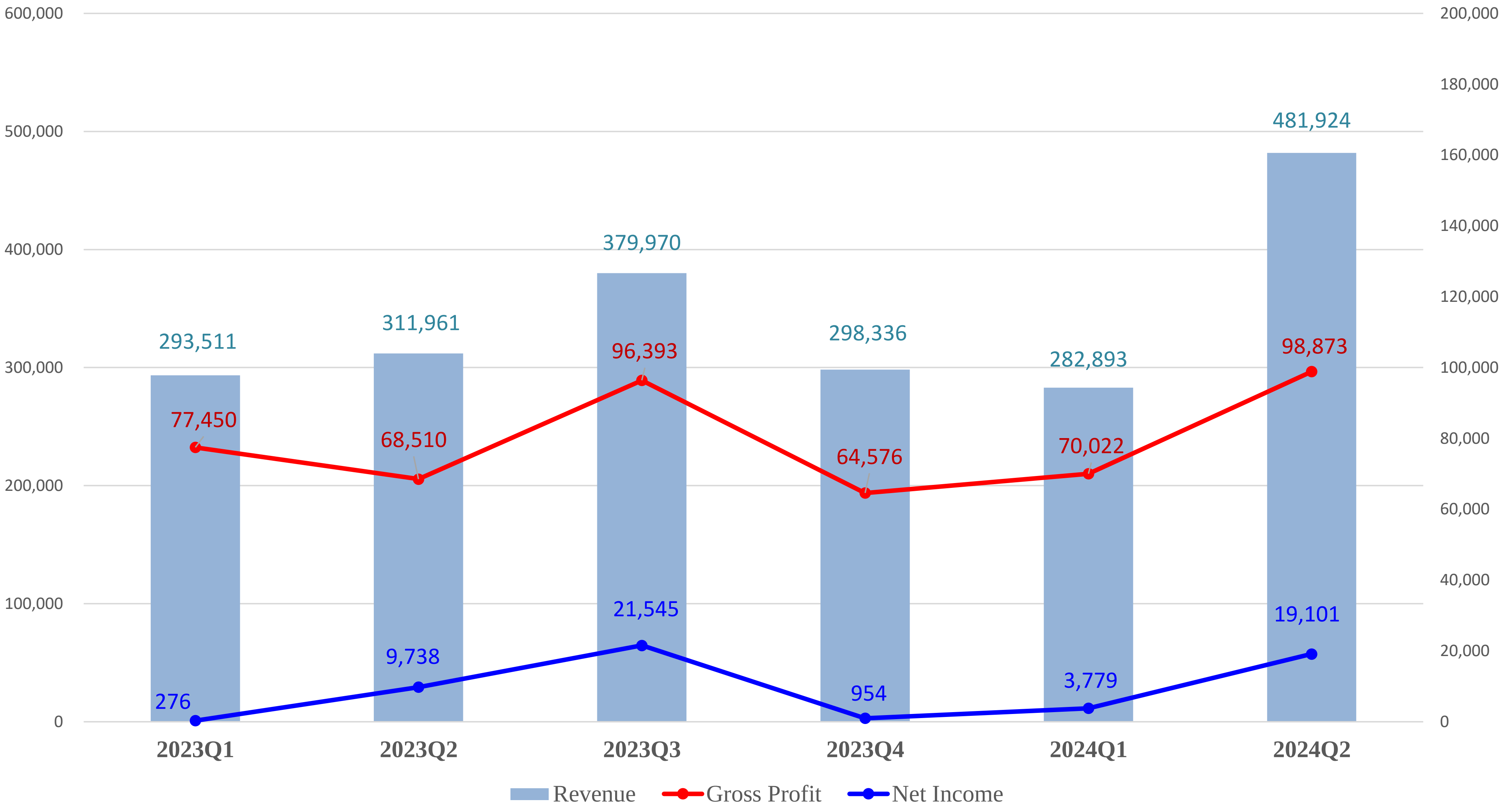
II. Operational Overview

Annual Revenue (NT$ thousand)



➢ Recent Quarterly Business Performance

II. Operational Overview



➢Dividend Policy

Adhering to a stable dividend policy, the dividend distribution over the past 5 years is as follows：

Unit：NT$

Year		2019	2020	2021	2022	2023
Dividend Policy	Cash	1.2	0.6	1.2	2	1.2
	Stock	-	1.2	-	-	-
Total		1.2	1.8	1.2	2	1.2

➢Outlook and Strategy of SynPower Group

1. SynPower

- 01 A+ glass substrate, in collaboration with the Industrial Technology Research Institute, has achieved A+ status. This involves a two-year development plan for advanced packaging processes and equipment for high aspect ratio glass substrates.
- 02 Promotion of optical inspection and measurement automation in the Thai PCB market.
- 03 Expanding the appearance inspection in premium smartphone.
- 04 Not just standalone machines, but integrated as a system sales model (OCA + Wet Process Equipment).
- 05 AI reduces inspection misjudgments and is applied to industries beyond PCB.

➢Outlook and Strategy of SynPower Group

2. SynTop

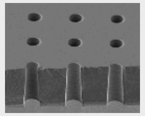
- Orders received from clients entering the Thailand in advance.
- Introduction of energy-saving fans.
- Development of glass substrate plating equipment.

➢ Integrating materials and equipment to provide a complete TGV solution.

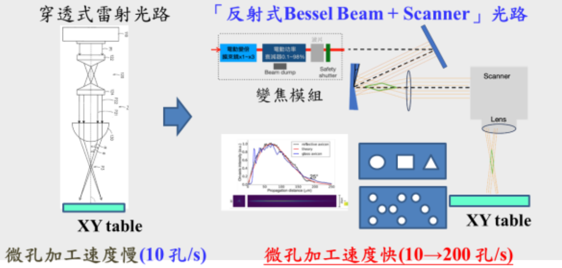
- Size: 8-12 inches, Aspect Ratio (AR) ≥ 20，Minimum Hole Diameter: 15 μm，Hole Density: OD x2，Hole Wall Perpendicularity: ≥ 88°

High Aspect Ratio Laser-Enhanced Deep Etching

Legend Laser



Processing Speed
-Array Holes: 5000 hole/s
- Non Array Holes: 200 hole/s
KOH Etching Equipment
- Hole Diameter Uniformity: >90%



微孔加工速度慢(10 孔/s)

微孔加工速度快(10→200 孔/s)

Development of High Aspect Ratio Glass Adhesion Layers

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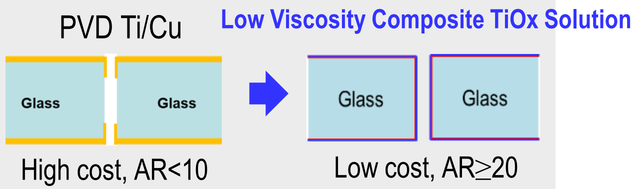
- Adhesion Layer Thickness: 100~200 nm
- Adhesion Strength: ≥ 5 N/cm
- Step Coverage: ≥ 65%
- Fully Wet Coating Equipment



PVD Ti/Cu

Low Viscosity Composite TiOx Solution

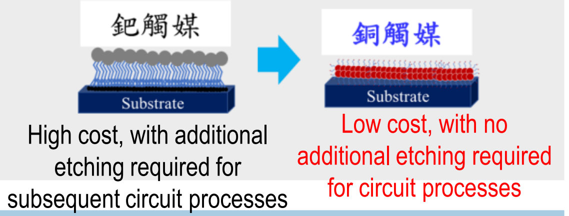
High cost, AR<10

Low cost, AR≥20

High Aspect Ratio Glass Seed Layer Copper Catalyst & High-Filling Chemical Copper Solution

Chinte Technology

- Seed Layer Thickness: ≥ 250 nm
- Catalyst Adsorption: ≤ 0.2 mg/dm²
- Step Coverage: ≥ 70%
- Adhesion: ASTM 5B @ 8 inches
- Fully Wet Chemical Deposition Equipment



High cost, with additional etching required for subsequent circuit processes

Low cost, with no additional etching required for circuit processes

High Aspect Ratio Glass Metallization and Via Filling Electroplating

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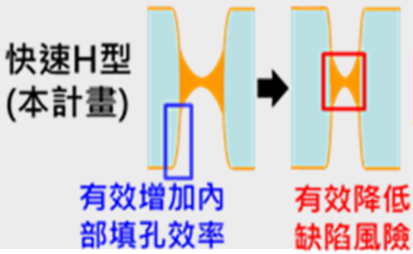
- Via Filling Yield: ≥ 95%
- Bridging Time: ≤ 1 hour
- Copper Thickness: ≤ 15 μm
- Fully Wet High Aspect Ratio Electroplating Equipment



快速H型
(本計畫)

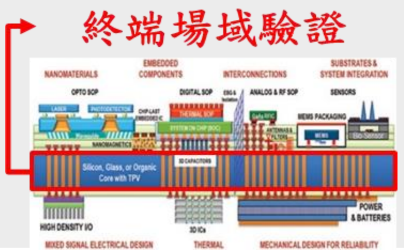
有效增加內部填孔效率

有效降低缺陷風險

TGV Substrate Patterning and Reliability Testing

Ecocera Optronics

- Adhesion Layer Removal
- RDL (Redistribution Layer) Circuit Fabrication
- 6 Types of Substrate Reliability Verification Tests



終端場域驗證

➢Outlook and Strategy of SynPower Group

3. Chipboard Technology

Establishing a Thin Nickel process outsourcing line for high-frequency applications.

Thank you for your guidance.